

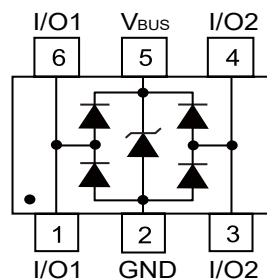
1.Description

UBT26A05L03 is designed to protect high speed data interfaces. It has been specifically designed to protect sensitive components which is connected to data and transmission lines from overvoltage caused by electrostatic discharge (ESD), electrical fast transients (EFT), and lightning. Low Capacitance 2-Line ESD Protection.

2.Features

- SOT23-6L surface mount package
- Protects three data lines
- Working voltage: 5V
- Low leakage current
- Low clamping voltage
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn 260~270°C

3.Pinning information



SOT23-6

4.Absolute Maximum Ratings $T_A = 25^\circ\text{C}$

Parameter	Symbol	Value	Units
Peak pulse current ($t_p=8/20\mu\text{s}$)	I_{pp}	5	A
ESD voltage (Contact discharge)	V_{ESD}	± 8	kV
ESD voltage (Air discharge)		± 15	kV
Storage temperature range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

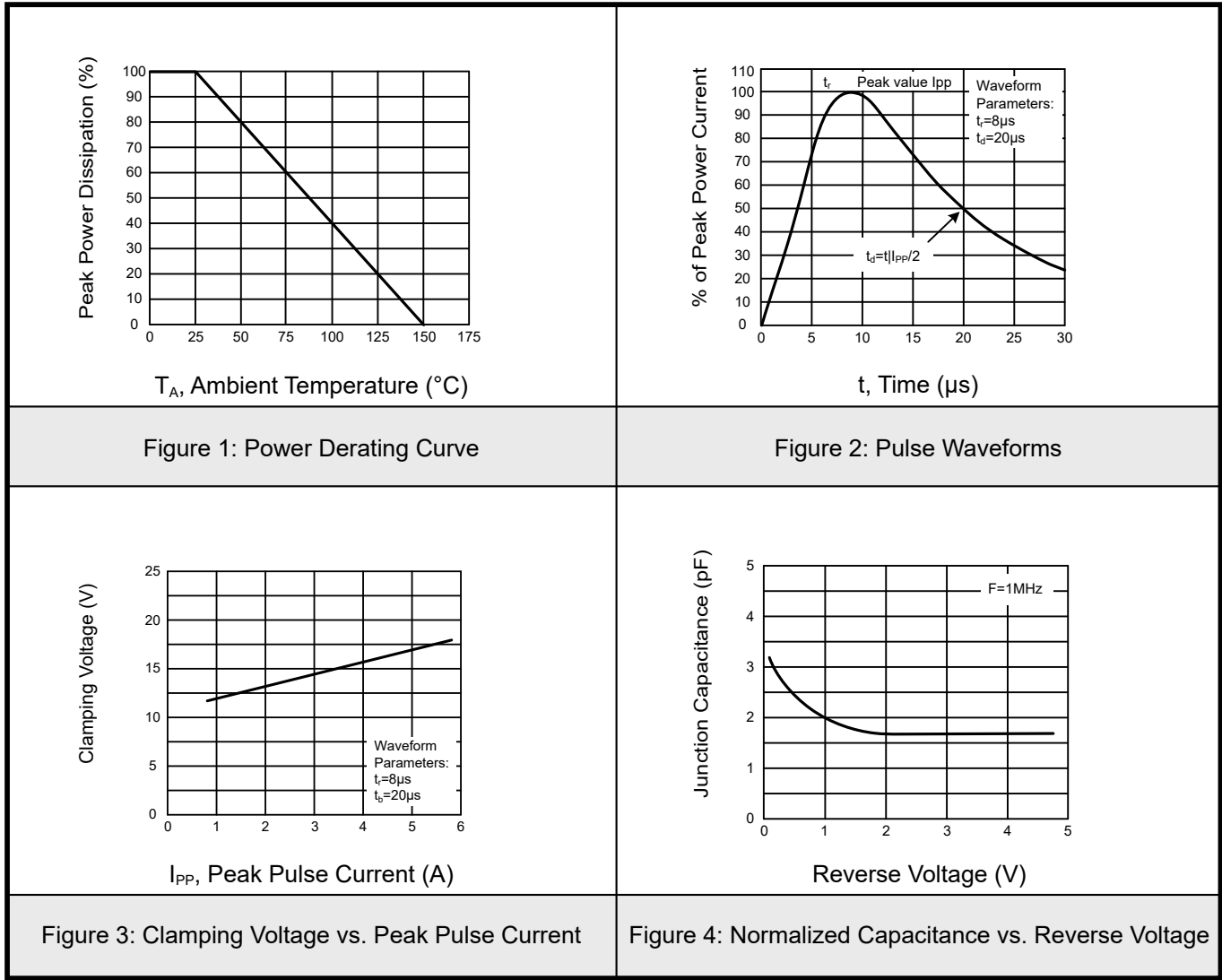


5. Electrical Characteristic ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Reverse stand-off voltage	V_{RWM}				5.25	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1\text{mA}$	6			V
Reverse leakage current	I_R	$V_R=5.25\text{V}$, Each I/O pin			1	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=1\text{A}$			12	V
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=5\text{A}$			17	V
Off state junction capacitance	C_J	0Vdc, $f=1\text{MHz}$ Between I/O pins and GND		3.5		pF



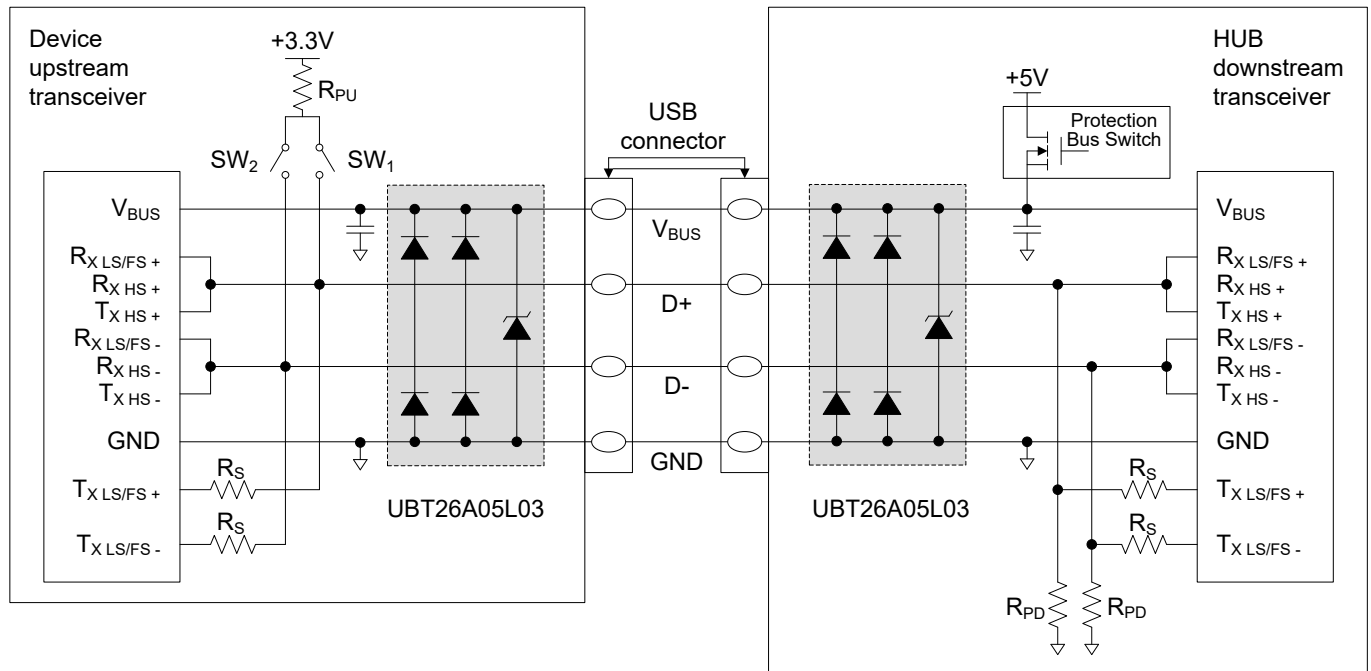
6. Typical characteristic





7.Applications Information

USB 2.0 port application diagram

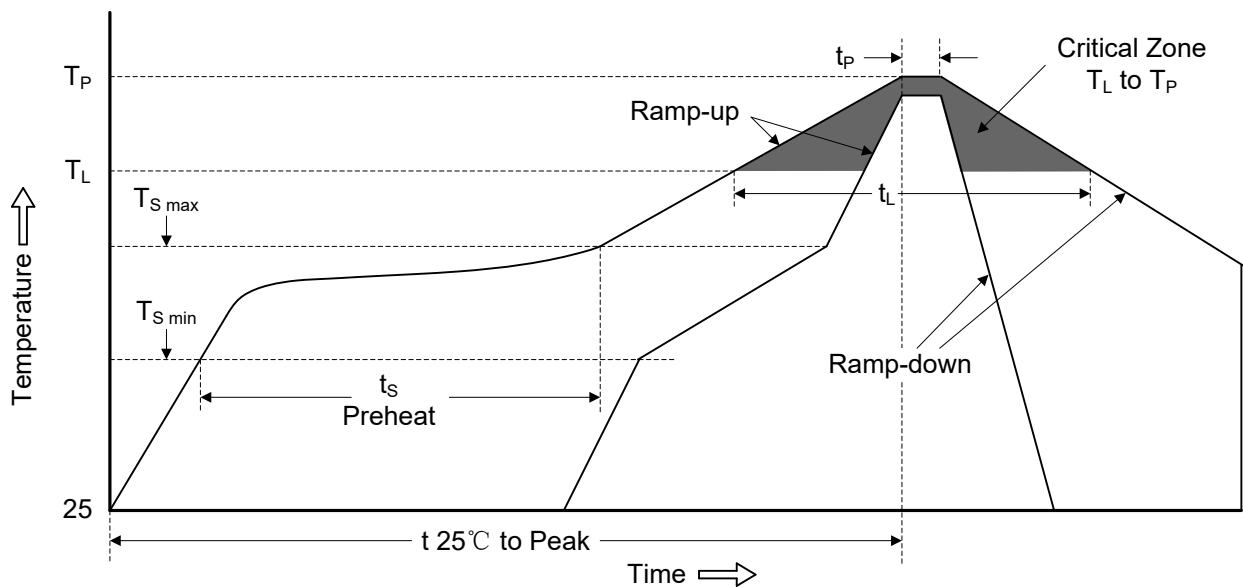


Mode	SW ₁	SW ₂
Low Speed LS	Open	Closed
Full Speed FS	Closed	Open
High Speed HS	Closed then open	Open



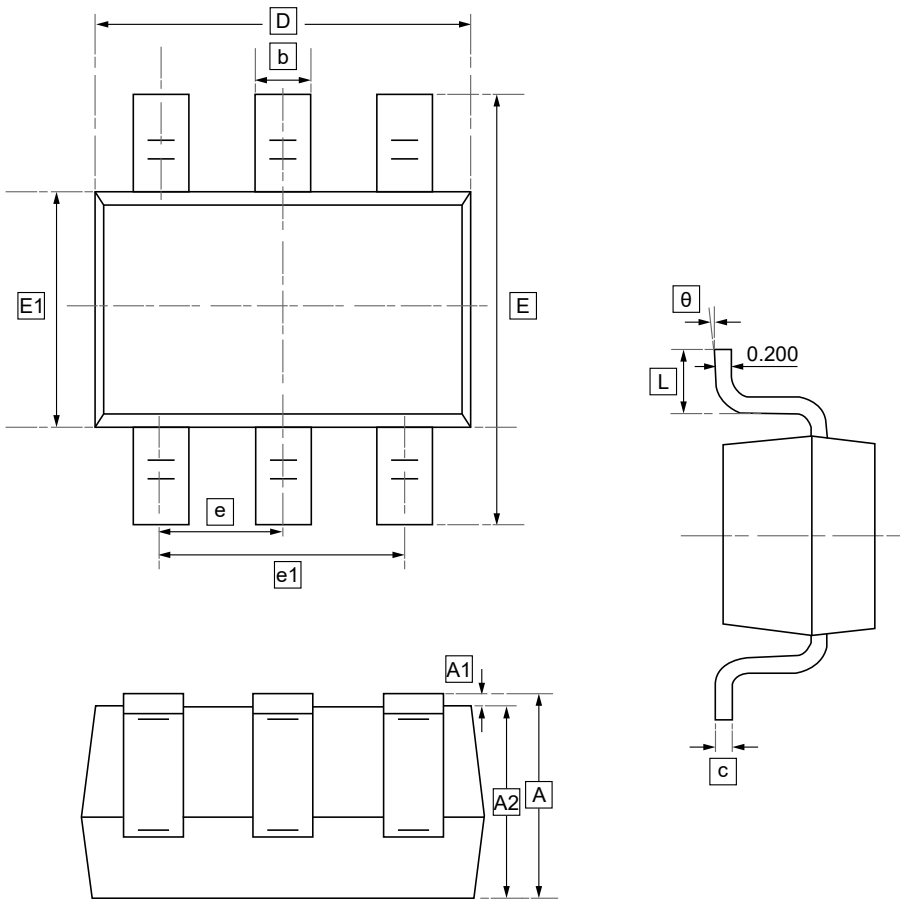
8. Soldering parameters

Profile Feature		Pb-Free Assembly
Average ramp-up rate (T_L to T_P)		3°C/second max.
Preheat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (ts)	60-180 secs.
T_{Smax} to T_L -Ramp-up Rate		3°C/sec. Max
Time maintained above:	-Temperature(T_L)	217°C
	-Time(T_L)	60-150 secs.
Peak Temperature (T_P)		+260°C
Time within 5°C of actual Peak Temp (T_P)		20-40 seconds
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temperature		8 min. Max





9.SOT-23-6 Package Outline Dimensions

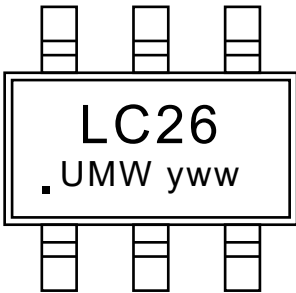


DIMENSIONS (mm are the original dimensions)

Symbol	A	A1	A2	b	c	D	E1	E	e	e1	L	θ
Min	1.050	0.000	1.050	0.300	0.100	2.820	1.500	2.650	0.950	1.800	0.300	0°
Max	1.250	0.100	1.150	0.500	0.200	3.020	1.700	2.950	BSC	2.000	0.600	8°



10.Ordering information



yww: Batch Code

Order Code	Package	Base QTY	Delivery Mode
UMW UBT26A05L03	SOT23-6	3000	Tape and reel



11.Disclaimer

UMW reserves the right to make changes to all products, specifications. Customers should obtain the latest version of product documentation and verify the completeness and currency of the information before placing an order.

When applying our products, please do not exceed the maximum rated values, as this may affect the reliability of the entire system. Under certain conditions, any semiconductor product may experience faults or failures. Buyers are responsible for adhering to safety standards and implementing safety measures during system design, prototyping, and manufacturing when using our products to prevent potential failure risks that could lead to personal injury or property damage.

Unless explicitly stated in writing, UMW products are not intended for use in medical, life-saving, or life-sustaining applications, nor for any other applications where product failure could result in personal injury or death. If customers use or sell the product for such applications without explicit authorization, they assume all associated risks.

When reselling, applying, or exporting, please comply with export control laws and regulations of China, the United States, the United Kingdom, the European Union, and other relevant countries, regions, and international organizations.

This document and any actions by UMW do not grant any intellectual property rights, whether express or implied, by estoppel or otherwise. The product names and marks mentioned herein may be trademarks of their respective owners.